

**DATA SHEET** 

#### DESCRIPTION

The LX8819 is a dual channel Voltages (typically ±1% of its specified Each channel features a low dropout typical @ 1A). and a high accuracy.

solution, minimal printed circuit board regulator output. area, and shorter design cycles.

design optimized for system efficiency designers by consuming minimal ground current component selection. while directing quiescent current to the load.

trimming of the internal voltage using surface mount technology. reference enabling precise output

positive-voltage linear regulator. This value) while the Bipolar output dual regulator has one fixed output transistor has a low dropout voltage coupled with an adjustable output. even at full output current ( $V_{DO} < 1.25V$ 

Thermal and Short Circuit Current The LX8819 provides designers Protection are integrated on-chip and with a flexible power management operate independently for each of the

The LX8819 regulator is stable with Each channel can supply up to one a low-value output capacitor (typically amp independently with a regulator 2.2µF on the outputs) allowing the flexibility in external

Microsemi's S-PAK and D-PAK power packages enable maximum The LX8819 features on-chip power dissipation and ease of assembly

IMPORTANT: For the most current data, consult MICROSEMI's website: http://www.microsemi.com

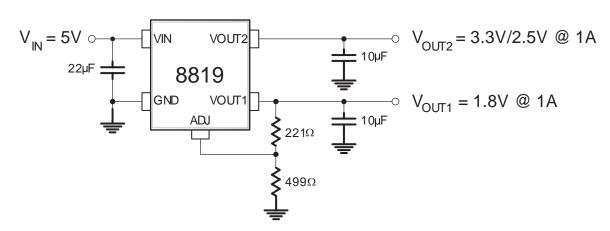
#### KEY FEATURES

- Two Independent Regulated Outputs
- **Accurate Output Voltages**
- Typical Dropout of 1.25V at 1A and 1.1V at 500mA
- Independent Thermal and Current Limit Protection
- Low Profile 5 Lead SMT Power Package
- Low Tolerance Load Regulation
- Wide DC Supply Voltage of 3.5V to 10V
- Loop Stability Independent of **Output Capacitor Type**

#### **APPLICATIONS**

- 5V to 3.3V / ADJ Regulators
- Hard Disk Drives, CD-ROMs
- ADSL and Cable Modems
- **Battery Charging Circuits**
- Instrumentation
- PC Peripherals

### PRODUCT HIGHLIGHT



	PACKAGE ORDER INFO								
	T <sub>J</sub> (°C)	Output V <sub>1</sub> (Pin 4)	Output V <sub>2</sub> (Pin 5)	RoHS Compliant	DT Plastic D-PAK 5-Pin				
				Transition DC: 0515					
	0 to 125 Adj. 3.3 <b>LX8819-3</b> 3		LX8819-33CDF	LX8819-33CDT					
L	0 10 120	Adj.	2.5	LX8819-25CDF	LX8819-25CDT				

Note: Available in Tape & Reel. Append the letters "TR" to the part number. (i.e. LX8819-33CDT-TR)



**DATA SHEET** 

### ABSOLUTE MAXIMUM RATINGS

Input Voltage (VIN)	13.5V
Load Current (Internally Limited)	1A
Power Dissipation	Internally Limited
Short-Circuit Protection	Indefinite
Operating Temperature Range	0°C to 150°C
Maximum Operating Junction Temperature	150°C
Storage Temperature Range	65°C to 150°C
Lead Temperature (Soldering 180 seconds)	235°C
RoHS Peak Package Solder Reflow Temperature	
(40 second maximum exposure)	260°C (+0, -5)

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

### THERMAL DATA

# **DF** Plastic S-PAK 5-Pin

THERMAL RESISTANCE-JUNCTION TO CASE, $\theta_{\text{JC}}$	5°C/W
THERMAL RESISTANCE-JUNCTION TO AMBIENT, $ heta_{JA}$	30°C/W

### **DT** Plastic D-PAK 5-Pin

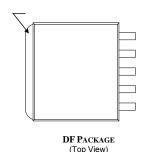
THERMAL RESISTANCE-JUNCTION TO CASE, $\theta_{JC}$	6°C/W
THERMAL RESISTANCE-JUNCTION TO AMBIENT. θιλ	32°C/W

Junction Temperature Calculation:  $T_J = T_A + (P_D x \theta_{JA})$ .

The  $\theta_{JA}$  numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.

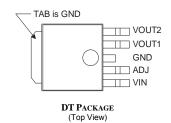
 $\theta_{JA}$  can vary from 25°C/W to > 40°C/W depending on mounting technique. (See Application Notes Section: Thermal considerations)

## PACKAGE PIN OUT



(TOP VIEW)

RoHS 100% Matte Tin Lead Finish



	FUNCTIONAL PIN DESCRIPTION						
Name Description							
VIN	Positive unregulated supply input for the regulator – Bypass to GND with at least 2.2µF capacitance having low ESR for good transient response.						
	Adjustable regulator feedback input – The output voltage can be set by two external resistors with the following relationship:						
ADJ	$VOUT1 = V_{REF} \cdot \left(1 + \frac{R_1}{R_2}\right) + I_{ADJ} \cdot R_1$						
	where $R_1$ is the resistor connected between VOUT1 and ADJ, and $R_2$ is the resistor connected between ADJ and GND.						
GND	Common terminal for ground reference – The input and output bypass capacitors should be connected to this pin. In addition the tab on the S-Pak package and pin 3 are also used for heat sinking the device.						
VOUT1	Adjustable regulator output (Regulator #1) – It is recommended to bypass to GND with at least 2.2µF. Size your output capacitor to meet the transient loading requirement. If you have a very dynamic load, a lower ESR capacitor will improve the response to these load steps.						
VOUT2	Fixed regulator output (Regulator #2) – It is recommended to bypass to GND with at least 2.2μF. Size your output capacitor to meet the transient loading requirement. For dynamic loads, a lower ESR capacitor will improve the response to these load steps.						



**DATA SHEET** 

### RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	LX8819			Units
r ai ailletei	Symbol	Min	Тур	Max	Ullits
Input Voltage - 3.3V	V <sub>IN</sub>	4.5		10	V
Input Voltage - 2.5V < 200mA Load		3.5		10	V
Output Voltage (Adjustable)	V <sub>OUT</sub>			5	V
Load Current (Each Output) <sup>1</sup>	I <sub>OUT</sub>	0		1000	mA
Input Capacitor (VIN to GND)	C <sub>IN</sub>	2.2	20		μF
Output Capacitor (VOUTx to GND) <sup>2</sup>	$C_OUT$	1.0	10		μF

- Note 1: Care should be taken so as to not exceed the thermal dissipation capability of the package
  - 2: Size your output capacitor to meet the transient loading requirement. If you have a very dynamic load, a lower ESR and larger value capacitor will improve the response to these load steps.

### **ELECTRICAL CHARACTERISTICS**

Unless otherwise specified, the following specifications apply over the operating ambient temperature  $0^{\circ}\text{C} \le \text{TA} \le 125^{\circ}\text{C}$  except where otherwise noted and with the following test conditions:  $V_{IN} = 5\text{V}$ ,  $I_{OUT} = 10\text{mA}$ ,  $C_{IN} = 10\mu\text{F}$  (Tantalum),  $C_{OUT} = 4.7\mu\text{F}$  (Tant.), and  $T_J = T_A$  using low duty cycling methods.

Parameter	Symbol	Test Conditions	Min Ty			Units	
1 diameter	Gyillooi	rest conditions		Тур	Max		
► ADJUSTABLE OUTPUT (VOUT1)							
Reference Voltage	$V_{REF}$	5mA < I <sub>OUT1</sub> < 1A, 4.75V < V <sub>IN</sub> < 5.5V	1.225	1.25	1.275	V	
Line Regulation	$\Delta V_{REF}(V_{IN})$	$3.75V < V_{IN} < 5.5V, I_{OUT1} = 5mA$		1.5	6	mV	
Load Regulation	$\Delta V_{REF}(I_{OUT})$	$5\text{mA} < I_{\text{OUT1}} < 1\text{A}, V_{\text{IN}} = 4.75\text{V}$		0.18	0.36	$%V_{\text{OUT}}$	
Dropout Voltage	ΔV	$I_{OUT1} = 1A, \Delta V_1 = -1\%$		1.3	1.46	V	
Current Limit	I <sub>OUT (MAX)</sub>		1.0	1.4		Α	
Minimum Load Current	IL	Note 3		2	3	mA	
Adjust Pin Bias Current	I <sub>ADJ</sub>			-0.12	-1	μΑ	
FIXED OUTPUT (OUTPUT 2)							
Output Voltage – LX8819-33	.,,	5mA < I <sub>OUT2</sub> < 1A, 4.75V < V <sub>IN</sub> < 5.5V	3.217	3.30	3.383	.,	
Output Voltage – LX8819-25	V <sub>OUT</sub>	5mA < I <sub>OUT2</sub> < 0.2A, 3.75V < V <sub>IN</sub> < 5.5V	2.437	2.5	2.562	V	
Line Regulation	$\Delta V_{OUT}(V_{IN})$	4.75V < V <sub>IN</sub> < 5.5V, I <sub>OUT2</sub> = 5mA		6	8	mV	
Load Regulation	$\Delta V_{OUT}(I_{OUT})$	5mA < I <sub>OUT2</sub> < 1A, V <sub>IN</sub> = 4.75V		6	12	mV	
Drangust Valtage	437	I <sub>OUT2</sub> = 1A, ΔV2 = -1%		1.25	1.41	V	
Dropout Voltage	ΔV	$I_{OUT2} = 0.2A, \Delta V2 = -1\%$			1.25	V	
Current Limit	I <sub>OUT (MAX)</sub>		1.0	1.4		Α	
Minimum Load Current	I <sub>OUT</sub>				0	mA	
► ENTIRE REGULATOR	•						
Outline and Outline at	,	V <sub>IN</sub> < 5.5V, I <sub>OUT1</sub> = 5mA, I <sub>OUT2</sub> = 5mA		2.6	4.2		
Quiescent Current	IQ	V <sub>IN</sub> ≤ 5.5V, I <sub>OUT1</sub> = 1A, I <sub>OUT2</sub> = 1A		3.5	5	mA	
VIN Under Voltage Lockout	UVLO	-3.3 Voltage Rising	2.5		4.5	V	
Threshold	OVLO	-2.5 Voltage Rising @ 25 °C	2.5		3.6	_ v	
V <sub>OUT</sub> Rise Time for VIN Switched On	V <sub>OUT</sub> (t <sub>R</sub> )		80		300	μS	
Ripple Rejection	PSRR	f=120Hz, V <sub>IN</sub> = 5V	60	75		dB	
RMS Output Noise	V <sub>OUT</sub> (RMS)	10Hz < f < 10kHz		0.003		%V <sub>OUT</sub>	
Thermal Shutdown	$T_{JSD}$		150	165		°C	

Note 3: Minimum load current is defined as the amount of output current required to maintain regulation. , The external resistor divider current can be included in this requirement.



**DATA SHEET** 

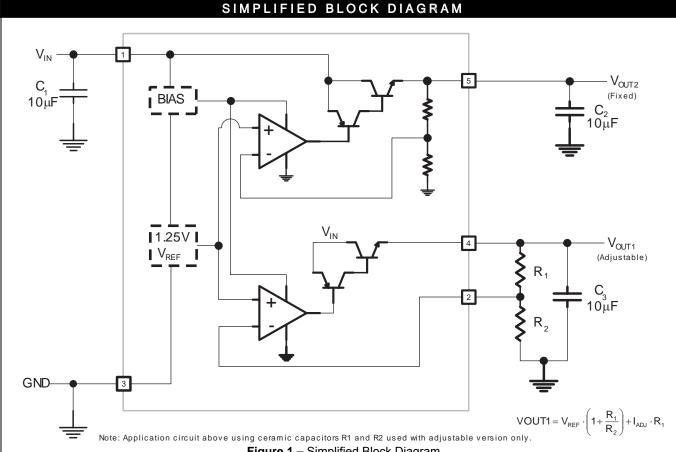


Figure 1 - Simplified Block Diagram



**DATA SHEET** 

#### APPLICATION INFORMATION

#### DESCRIPTION

The LX8819 is part of a family of Dual LDO (Low Drop-Out) linear regulators in Microsemi's S-PAK power package which offer maximum power dissipation in a low profile surface mount technology. The family includes a combination of fixed and adjustable versions. Each channel can supply up to one amp independently with a regulator design optimized for system efficiency by consuming minimal ground current and directing quiescent current to the load.

#### INPUT CAPACITOR

To improve load transient response and noise rejection an input bypass capacitor of at least  $2.2\mu F$  is required. Generally it is recommended that a  $20\mu F$  ceramic/tantalum or  $22\mu F$  electrolytic capacitor be used.

#### **OUTPUT CAPACITOR**

The LX8819 regulator requires output capacitors connected between each voltage output and ground to stabilize the internal control loop. Many types of capacitors, with different capacitance values, tolerances, temperature coefficients, and equivalent series resistance are available for use with the LX8819. It is recommended that a minimum of  $4.7\mu F$  be used at each voltage output.

To ensure good transient response from the power supply system under rapidly changing current load conditions, designers generally use additional output capacitors connected in parallel. Such an arrangement serves to minimize the effects of the parasitic resistance (ESR) and inductance (ESL) that are present in all capacitors. The regulator has been tested stable with capacitor ESR's in the range of  $50m\Omega$  to  $2\Omega$ . It is generally best to use the same type of capacitors for both input and output bypassing.

#### ADJUSTABLE OUTPUT VOLTAGE

The LX8819 develops a 1.25V reference voltage between the adjust terminal and ground (See Figure 2). By placing a resistor,  $R_2$ , between these two terminals, a constant current is caused to flow through  $R_1$  and down through  $R_2$  to set the overall output voltage. Because  $I_{ADJ}$  is very small and constant when compared with the current through  $R_2$ , it represents a small error and can usually be ignored.

#### MINIMUM LOAD REQUIREMENT

The LX8819 has a minimum load requirement for proper output regulation. This minimum current is specified at 0mA for the fixed output and 2mA for the adjustable output regulator.

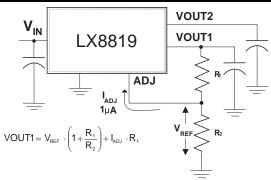


Figure 2 - Basic Regulator Circuit

#### TEMPERATURE PROTECTION

The thermal protection shuts the LX8819 down when the junction temperature exceeds 140°C. Each output has independent thermal shutdown capability. Exposure to absolute maximum rated conditions for extended periods may affect device reliability (See Thermal Considerations below).

### **CURRENT LIMIT PROTECTION**

The LX8819 includes over current protection. When the output load current exceeds 1.4A (typical) the current limit protection circuit forces the regulator to decrease the output current in order to maintain safe levels.

#### THERMAL CONSIDERATIONS

Thermal shutdown protection circuitry protects the integrated circuit from thermal overload caused from a rise in junction temperature during excessive power dissipation conditions. This means of protection is intended for fault protection only and not as a means of current or power limiting during normal application usage.

Proper thermal evaluation should be done to ensure that the junction temperature  $(T_J)$  does not exceed its maximum rating. Continuous operation at the maximum  $T_J$  of 150°C can impact reliability.

Due to variation in individual device electrical characteristics and thermal resistance, the built in thermal overload protection may be activated at power levels slightly above or below the rated dissipation. Also, peak output power should be considered for each individual output.

Total power dissipation for the regulator can be calculated using the following equation:

$$\mathsf{P}_{\mathsf{D}} = \left(\mathsf{V}_{\mathsf{IN}(\mathsf{MAX})} - \mathsf{V}_{\mathsf{OUT1}}\right) \cdot \mathsf{I}_{\mathsf{OUT1}} + \left(\mathsf{V}_{\mathsf{IN}(\mathsf{MAX})} - \mathsf{V}_{\mathsf{OUT2}}\right) \cdot \mathsf{I}_{\mathsf{OUT2}}$$

(Note: Power dissipation resulting from quiescent (ground) current is negligible and ignored)



**DATA SHEET** 

#### APPLICATION INFORMATION

Using the calculated total power dissipation, the maximum junction temperature can be calculated using the given temperature coefficients (See Thermal Data) for the selected package.

#### THERMAL CALCULATION EXAMPLE

Given the following application parameters:

$$\begin{split} T_{A} &= 50^{\circ}C \\ V_{IN(MAX)} &= 5V + 5\% \\ V_{OUT1} &= 1.5V \\ V_{OUT2} &= 2.5V \\ I_{OUT1(MAX)} &= I_{OUT2(MAX)} = 500mA \end{split}$$

The maximum junction temperature of the LX8819 can be calculated using the following equation:

$$T_{J} = T_{A} + (P_{D(REG1)} + P_{REG2}) \cdot \theta_{JA}$$

with:

$$\begin{split} P_{D(REG1)} &= \left(V_{IN(MAX)} - V_{OUT1}\right) \cdot I_{OUT1} \\ &\quad and \\ P_{D(REG2)} &= \left(V_{IN(MAX)} - V_{OUT2}\right) \cdot I_{OUT2} \end{split}$$

Substituting the known values yields a maximum junction temperature of:

 $P_{D(RFG1)} = (5.25V - 1.5V) \cdot 0.5A = 1.75W$ 

$$\begin{split} P_{D(REG2)} &= \left(5.25V - 2.5V\right) \cdot 0.5A = 1.375W \\ T_{J} &= T_{A} + \left(P_{D(REG1)} + P_{D(REG2)}\right) \cdot \theta_{JA} \\ T_{J} &= 50^{\circ}C + \left(1.75W + 1.375W\right) \cdot 30\frac{^{\circ}C}{W} \end{split}$$

This value is within the safe operating range of the device under worst case conditions

It is important to note that although each output of the regulator will produce up to 1A in current, the individual or total power dissipation may limit the useful total current draw. The junction temperature should be calculated for each individual output as well as the combined outputs to insure that maximum junction temperature in not exceeded.

#### **LAYOUT CONSIDERATION**

The layout must be done with low impedance paths for VIN, VOUT1, VOUT2 and GND by using sufficiently wide traces to avoid voltage drops and noise pick up. The output capacitors must be placed as close as possible to the voltage regulator output pins.

The input capacitor should be connected between VIN and the ground plane with short leads.

Although it may not be immediately obvious, best load regulation for the adjustable output is obtained when the top of the voltage feedback resistor divider  $(R_1)$  is connected as close as possible to the case of the regulator; not to the load.

The PCB copper can be used as a heatsink for the surface mounted package. Using the minimum size as shown in the recommended pad layout (Figure 3), limits the usable power to about 1W for an ambient temperature of 50°C. Since most applications require greater than 2W there is the need to provide additional heatsinking. This can be accomplished by using additional copper area both on the PCB surface, as shown in the possible heat sink layout below, or to an embedded ground plane. Since the die pad (copper tab) is in electrical contact with ground, the designer can use thermal vias, on the surface of the PCB, taking advantage of the heat-spreading (Cu) layer of an internal ground plane.

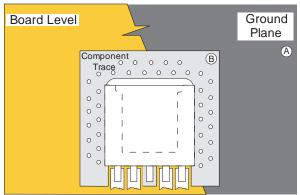


Figure 3 - Recommended Layout

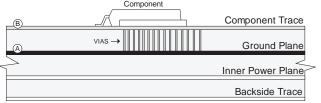
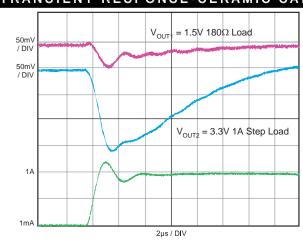


Figure 4 – Ground Plane Heatsink



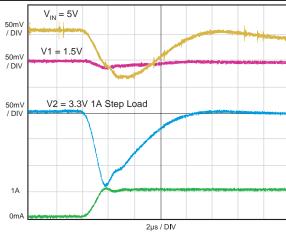
**DATA SHEET** 





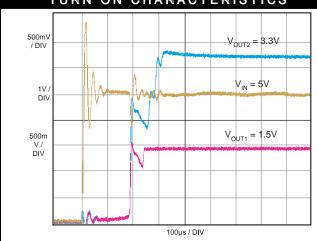
 $C_{IN} = 20\mu F$  Ceramic (ESR=  $45m\Omega$ ) COUT(VOUT1) = COUT(VOUT2) =  $10\mu$ F Ceramic (ESR=  $75m\Omega$ )

#### TRANSIENT **RESPONSE-TANT** CAP

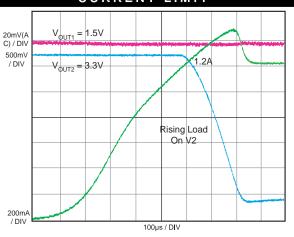


 $C_{IN} = 22\mu F Tantalum (ESR= 232m\Omega)$  $C_{\text{OUT(VOUT1)}} = C_{\text{OUT(VOUT2)}} = 10 \mu \text{F Tantalum (ESR= 198m}\Omega)$ 

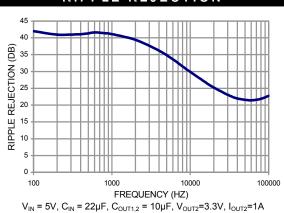
### TURN ON CHARACTERISTICS



#### **CURRENT LIMIT**



#### REJECTION



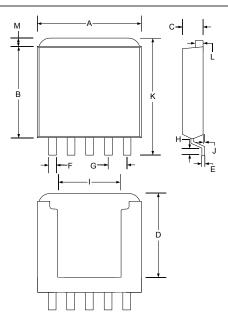
Copyright © 2003 Revision 1.0a, 4/29/2005



**DATA SHEET** 

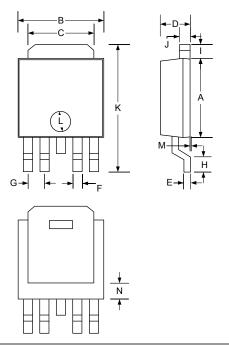
### PACKAGE DIMENSIONS

### DIT 5-Pin S-PAK



	MILLIM	MILLIMETERS		HES	
Dim	MIN	MAX	MIN	MAX	
Α	9.27	9.52	0.365	0.375	
В	7.87	8.13	0.310	0.320	
С	1.78	2.03	0.070	0.080	
D	2.80	3.10	0.110	0.122	
Е	1.50	1.75	0.059	0.069	
F	0.63	0.79	0.025	0.031	
G	1.70	BSC 0.0		7 BSC	
Н	0.79	1.04	0.031	0.041	
I	6.50	BSC	0.256 BSC		
J	0.03	0.13	0.001	0.005	
K	10.41	10.67	0.410	0.420	
L	0.76	1.27	0.030	0.050	

# **DT** 5-Pin TO-252 (D-PAK)



	MILLIM	IETERS	INCHES		
Dim	MIN	MAX	MIN	MAX	
Α	5.96	6.22	0.234	0.244	
В	6.47	6.73	0.254	0.264	
С	5.00	5.22	0.196	0.205	
D	2.18	2.38	0.085	0.093	
E	0.45	0.55	0.017	0.021	
F	0.63	0.78	0.024	0.030	
G	1.27 BSC		0.050 BSC		
Н	1.08	1.29	0.042	0.050	
I	1.01	1.11	0.039	0.043	
J	0.76	0.86	0.029	0.033	
K	9.70	10.08	0.381	0.396	
L	1.52	1.62	0.059	0.063	
М	0.03	0.13	0.001	0.005	
N	1.27 REF		.05 REF		

**Note:** Dimensions do not include mold flash or protrusions; these shall not exceed 0.155mm(.006") on any side. Lead dimension shall not include solder coverage.



LX8819

## **Dual Channel 1A Low Dropout Regulator**

**DATA SHEET** 

NOTES

PRODUCTION DATA – Information contained in this document is proprietary to Microsemi and is current as of publication date. This document may not be modified in any way without the express written consent of Microsemi. Product processing does not necessarily include testing of all parameters. Microsemi reserves the right to change the configuration and performance of the product and to discontinue product at any time.